

SLOVENSKI STANDARD

SIST EN 61709:2017

01-julij-2017

Nadomešča:
SIST EN 61709:2011

Električne komponente - Zanesljivost - Referenčni pogoji za pogostost odpovedi in modele obremenjevanja za pretvarjanje (IEC 61709:2017)

Electric components - Reliability - Reference conditions for failure rates and stress models for conversion (IEC 61709:2017)

Elektrische Bauelemente - Zuverlässigkeit - Referenzbedingungen für Ausfallraten und Beanspruchungsmodelle zur Umrechnung (IEC 61709:2017)

Composants électriques - Fiabilité - Conditions de référence pour les taux de défaillance et modèles de contraintes pour la conversion (IEC 61709:2017)

Ta slovenski standard je istoveten z: EN 61709:2017

ICS:

21.020	Značilnosti in načrtovanje strojev, aparatov, opreme	Characteristics and design of machines, apparatus, equipment
31.020	Elektronske komponente na splošno	Electronic components in general

SIST EN 61709:2017

en

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EUROPEAN STANDARD

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Electric components - Reliability - Reference conditions for failure rates and stress models for conversion (IEC 61709:2017)

Composants électriques - Fiabilité - Conditions de référence pour les taux de défaillance et modèles de contraintes pour la conversion
(IEC 61709:2017)

Bauelemente der Elektronik - Zuverlässigkeit - Referenzbedingungen für Ausfallraten und Beanspruchungsmodelle zur Umrechnung
(IEC 61709:2017)

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SIST EN 61709:2017

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Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Avenue Marnix 17, B-1000 Brussels

EN 61709:2017**European foreword**

The text of document 56/1714/FDIS, future edition 3 of IEC 61709, prepared by IEC/TC 56 "Dependability" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 61709:2017.

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- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2017-12-24
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2020-03-24

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In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 60300-3-2:2004	NOTE	Harmonized as EN 60300-3-2:2005.
IEC 60300-3-3	NOTE	Harmonized as EN 60300-3-3.
IEC 60721 (series)	NOTE	Harmonized as EN 60721 (series).
IEC 60721-3-3	NOTE	Harmonized as EN 60721-3-3.
IEC 60721-3-4	NOTE	Harmonized as EN 60721-3-4.
IEC 60721-3-5	NOTE	Harmonized as EN 60721-3-5.
IEC 60721-3-7	NOTE	Harmonized as EN 60721-3-7.
IEC 61014:2003	NOTE	Harmonized as EN 61014:2003.
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IEC 61360-1:2009	NOTE	Harmonized as EN 61360-1:2010.
IEC 61360-4:2005	NOTE	Harmonized as EN 61360-4:2005.
IEC 61508 (series)	NOTE	Harmonized as EN 61508 (series).
IEC 61649:2008	NOTE	Harmonized as EN 61649:2008.
IEC 61703:2002	NOTE	Harmonized as EN 61703:2002.
IEC 61710	NOTE	Harmonized as EN 61710.

IEC 61810-2:2011	NOTE	Harmonized as EN 61810-2:2011.
IEC 61810-2-1:2011	NOTE	Harmonized as EN 61810-2-1:2011.
IEC 62007 (series)	NOTE	Harmonized as EN 62007 (series).
IEC 62741	NOTE	Harmonized as EN 62741.
IEC 62308:2006	NOTE	Harmonized as EN 62308:2006.

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EN 61709:2017

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60050-192	2015	International electrotechnical vocabulary - Part 192: Dependability	-	-

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Electric components – Reliability – Reference conditions for failure rates and stress models for conversion

Composants électriques – Fiabilité – Conditions de référence pour les taux de défaillance et modèles de contraintes pour la conversion

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**ELECTRIC COMPONENTS –
RELIABILITY –
REFERENCE CONDITIONS FOR FAILURE RATES
AND STRESS MODELS FOR CONVERSION****FOREWORD**

- 1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as “IEC Publication(s)”). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
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International Standard IEC 61709 has been prepared by IEC technical committee 56: Dependability.

This third edition cancels and replaces the second edition, published in 2011. This edition constitutes a technical revision. This third edition is a merger of IEC 61709:2011 and IEC TR 62380:2004.

This edition includes the following significant technical changes with respect to the previous edition:

- a) addition of 4.5 Components choice, 4.6 Reliability growth during the deployment phase of new equipment, 4.7 How to use this document, and of Clause 19 Printed circuit boards (PCB) and Clause 20 Hybrid circuits with respect to IEC TR 62380;
- b) addition of failure modes of components in Annex A;